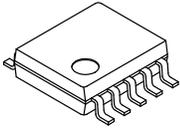


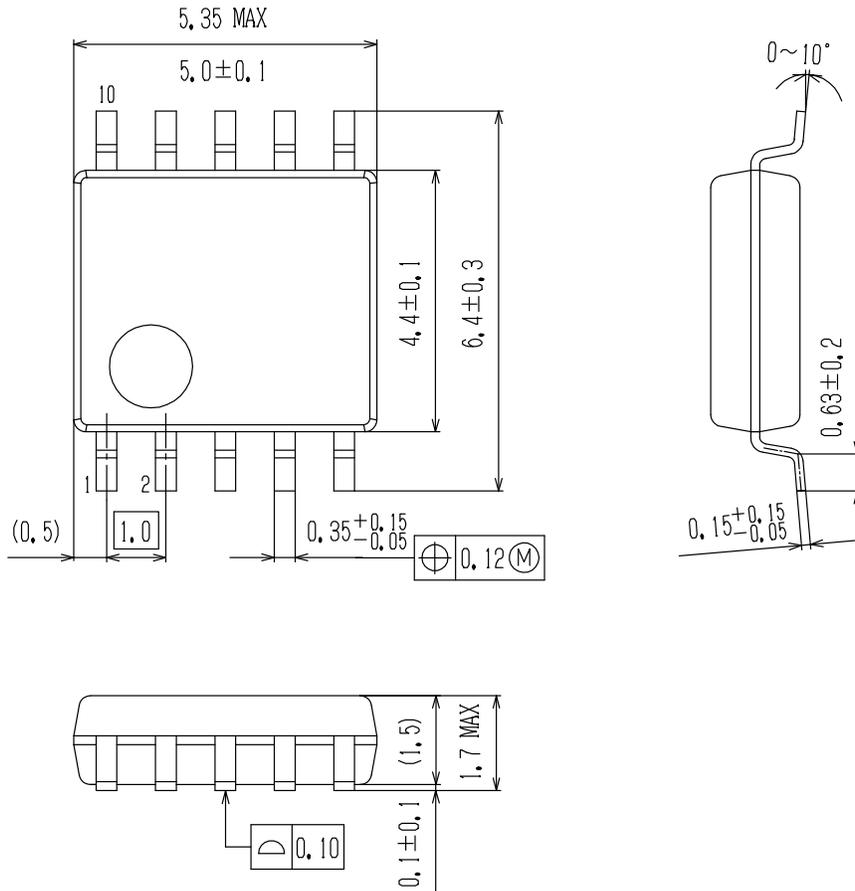
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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SOIC10 W / MFP10S (225 mil)
CASE 751BX
ISSUE 0

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